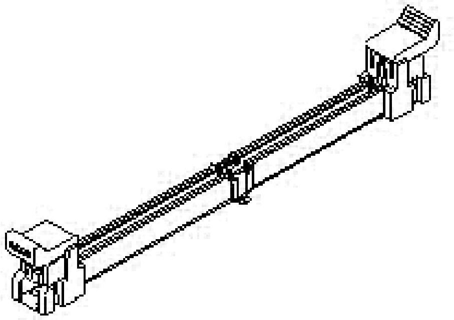
Part Number : 877822201

Product Description : 0.60mm Pitch miniDIMM Socket, Surface Mount, Vertical, 1.8V Voltage Key, 200 Circuits, 0.76µm Gold (Au) Plating, Off-White Latches, without Pick-and-Place Cap, Lead-Free

Series Number : 87782

Status : Obsolete

Product Category : Memory Module Connectors



Documents & Resources

Drawings

877822201_sd.pdf

3D Models and Design Files

STEP AP242

SOLIDWORKS

Creo

EE-87782-001-001.pdf

EE-87782-002-001.pdf

EE-87782-003-001.pdf

EE-87782-007-001.pdf

SP-87782-001-001.zip

SP-87782-007-001.zip

Specifications

AS-87782-001-001.pdf

PS-87782-027-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	ⓔ per SJ/T 11365-2006
EU ELV	Not Relevant

Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Obsolete
Category	Memory Module Connectors
Series	87782
Description	0.60mm Pitch miniDIMM Socket, Surface Mount, Vertical, 1.8V Voltage Key, 200 Circuits, 0.76µm Gold (Au) Plating, Off-White Latches, without Pick-and-Place Cap, Lead-Free
Component Type	Socket
JEDEC Outline	MO-258
Product Name	MiniDIMM
UPC	822348683857

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	1.8V
Voltage - Maximum	30V (RMS)

Physical

Circuits (Loaded)	200
Circuits (maximum)	200
Durability (mating cycles max)	25
Entry Angle	Vertical (Top Entry)
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Natural (Off-White)
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	3.660/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
Pitch - Mating Interface	0.60mm
Pitch - Termination Interface	0.60mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	5
Lead-Free Process Capability	SMC&WAVE

Max-Cycle	2
Max-Temp	260

Mates With / Use With

Mates with Part(s)

Description	Part Number
Mates With	JEDEC MO-258 Modules

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